

## RX630 Group

### Communication with EEPROM Using the Serial Communications Interface (Simple I<sup>2</sup>C)

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#### Introduction

This application note describes communication with a connected EEPROM using the simple I<sup>2</sup>C function of the RX630 Group SCI (serial communications interface) module.

#### Target Device

RX630 Group

This application note can also be used with other RX family microcontrollers that have the same I/O registers (peripheral unit control registers) as the RX630 Group products. Note, however, that since there are changes between devices, such as additional functionality in certain functions, these operations must be verified with the manual for the device actually used. When using the methods described in this application note, full testing in the actual user system is required.

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## 1. Specifications

This sample program uses the SCI (serial communications interface) simple I<sup>2</sup>C function to communicate with an EEPROM and write 8 bytes of data to that EEPROM. It then reads back that 8 bytes of data.

Table 1.1 lists the peripheral functions used and their uses.

**Table 1.1 Peripheral Functions and their Uses**

<b>Peripheral Function</b>	<b>Use</b>
SCI (serial communications interface)	<ul style="list-style-type: none"><li>• Simple I<sup>2</sup>C function</li><li>• Transfer rate: 100 kHz</li><li>• Master/slave mode: single master mode</li></ul>

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## 2. Conditions of Checking the Operation of the Software

The sample code described in this application note has been confirmed to run normally under the operating conditions given below.

**Table 2.1    Operating Conditions**

<b>Item</b>	<b>Description</b>
MCU	RX630 (R5F5630EDDFP)
Memory used for evaluation	Xin clock: 12 MHz Subclock: 32.768 kHz
Operating voltage	3.3 V
Integrated development environment	Version 4.09.00.007
C compiler	RX Standard Toolchain (V.1.0.1.0)  C/C++ compiler package for RX family V.1.01.00 Compiler options: The default settings for the integrated development environment are used.
Operating mode	Single chip mode
Version of the sample code	Version 1.40
Board used	R0K505630C001BR

### 3. Software Description

#### 3.1 Operation Overview

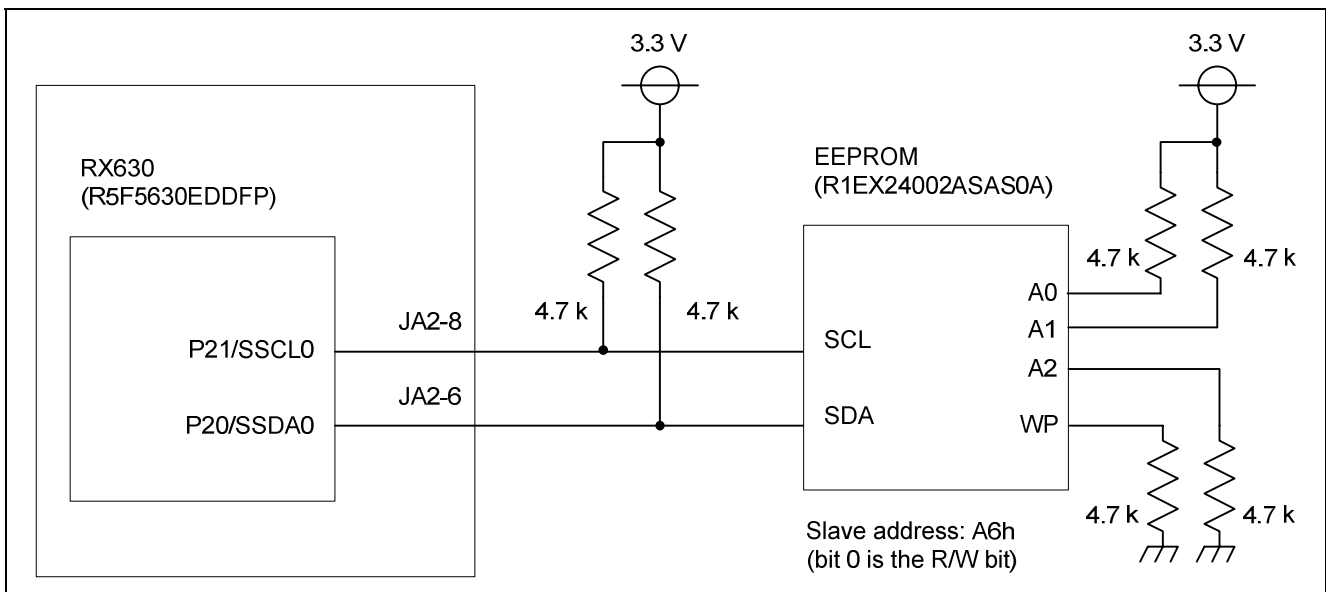
The simple I<sup>2</sup>C bus format consists of 8 bits of data plus one acknowledge bit. The frame, which follows a start condition or restart condition, is a slave address frame and is used to specify the slave device which is the communication destination for the master device. The specified slave device is valid until either a new slave device is specified or a stop condition is issued. Each 8-bit data item in the frame is transmitted in order starting with the MSB.

Although both the SCI c and SCI d SCI modules support simple I<sup>2</sup>C mode, this application note uses channel 0 in SCI c.

#### 3.1.1 Specifications

This application note communicates with an EEPROM and writes 8 bytes of data to that EEPROM. It then reads back that 8 bytes of data.

Figure 3.1 shows the connections used for this application note.



**Figure 3.1 Connection Diagram**

Table 3.1 lists the SCI communication function settings and conditions used in this application note.

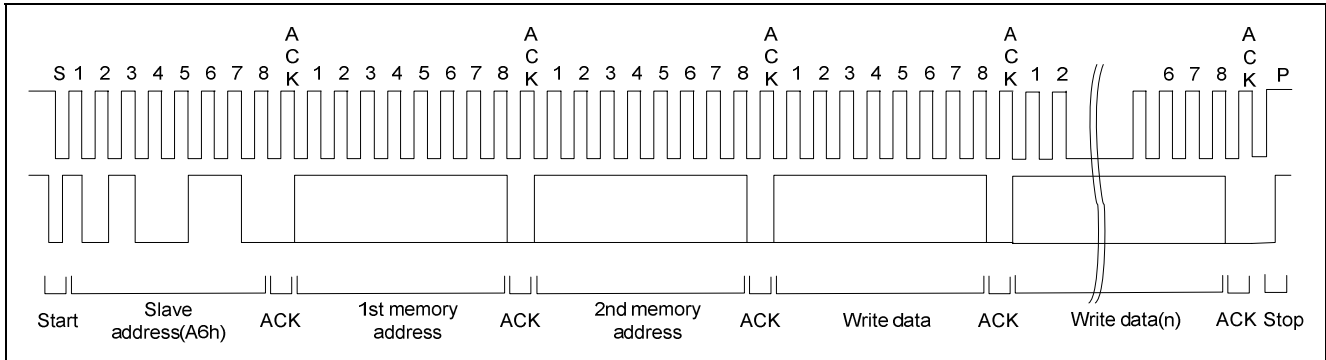
**Table 3.1 SCI Settings and Conditions**

Channels used	SCI0
Communication mode	Simple I <sup>2</sup> C mode
Interrupts	Unused
Transfer rate	100 KHz
Master/slave mode	Single master mode
Address format	7-bit address format

**3.1.2 Writing to EEPROM**

This sample program uses master mode transmission to write to an EEPROM. The RIIC generates a start condition (S) and then transmits the EEPROM slave address. Since the eighth bit here is the R/W bit, a 0 is transmitted for writing (master transmission). It then sends sequentially the memory address, which consists of two 8-bit units, and then the data to be written to the EEPROM. The two 8-bit unit memory address transmitted here indicates the address in the EEPROM to be written. After all the data has been written the sample program issues a stop condition (P) to release the bus. Note that the memory address written by this program is 0000h.

Figure 3.2 shows examples of the signals used when writing to EEPROM.

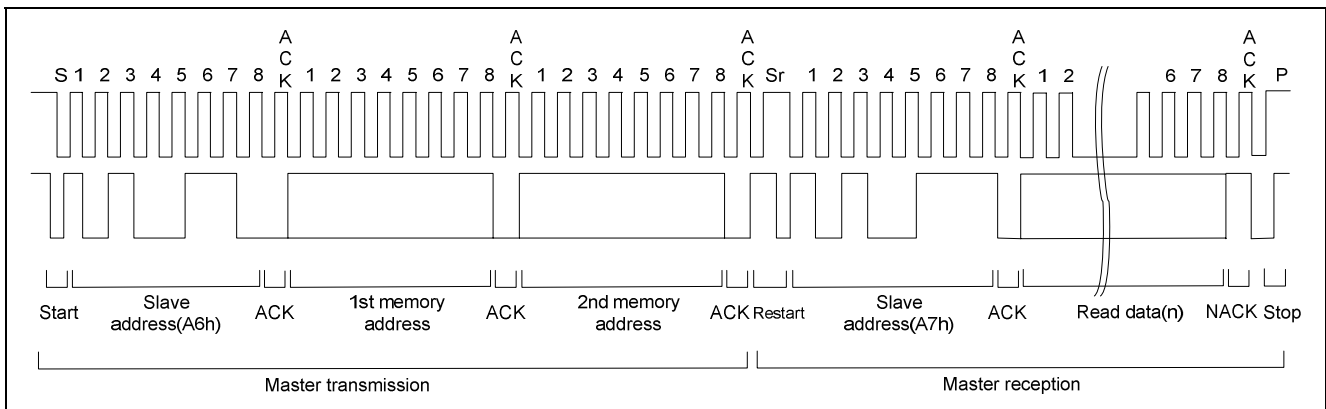


**Figure 3.2 Signals when Writing to EEPROM**

**3.1.3 Reading from EEPROM**

This sample program uses master transmission and master reception (compound format) to read data from the EEPROM. First, the RIIC generates a start condition (S) and then transmits the EEPROM slave address as two 8-bit units. In the EEPROM slave address transmission here, a 0 is transmitted for the R/W bit (master transmission). Then, it generates a restart condition (Sr) and transmits the EEPROM slave address again. In the EEPROM slave address transmission here, a 1 is transmitted for the R/W bit (master reception). After transmitting the EEPROM slave address, the RIIC reads out the EEPROM data by continuing to generate the clock. During this read operation, the RIIC issues an ACK after receiving each byte. However, it returns a NACK after the last byte, and only after the last byte. It then generates a stop condition (P). Note that the memory address read by this program is 0000h.

Figure 3.3 shows examples of the signals used when reading from EEPROM.



**Figure 3.3 Signals when Reading from EEPROM**

### 3.2 File Structure

Table 3.2 lists the files used in the sample code.

**Table 3.2 File Structure**

File Name	Function	Notes
main_i2c.c	<ul style="list-style-type: none"> <li>The main processing</li> <li>Interrupt grouping control related processing</li> <li>SCI interrupt processing</li> </ul>	
dbstc.c	B and R section settings	File automatically generated by the IDE
intprg.c	Interrupt handling (The SCI interrupt handler, which is used by this program, has been removed from this file.)	File automatically generated by the IDE
resetprg.c	Reset handling	File automatically generated by the IDE
sbrk.c	sbrk() function	File automatically generated by the IDE
vecttbl.c	Vector table related processing	File automatically generated by the IDE to which option and memory settings have been added
iodefine.h	I/O register related header file	
lowsrc.h	I/O streams related header file	File automatically generated by the IDE
sbrk.h	sbrk() function header file	File automatically generated by the IDE
stacksct.h	Stack area header file	File automatically generated by the IDE
typedefine.h	Integer type definitions header file	File automatically generated by the IDE
vect.h	Vector table related header file	File automatically generated by the IDE

### 3.3 Constants

Table 3.3 lists the constants used by the sample code.

**Table 3.3 Constants Used in the Sample Code**

Constant	Set Value	Description
TARGET_SLAVE_ADDRESS	0xA6	EEPROM slave address
EEPROM_ADDRESS_LENGTH	2	EEPROM slave address length

### 3.4 Variables

Table 3.4 lists the global variables.

**Table 3.4 Global Variables**

Type	Name	Description	Functions Where Used
unsigned char	trm_eeeprom_adr[2]	EEPROM slave address storage buffer (during write)	main, IIC_EepWrite
unsigned char	rcv_eeeprom_adr[2]	EEPROM slave address storage buffer (during read)	main, IIC_EepRead
unsigned char	trm_buff[256]	Transmit data buffer	main, IIC_EepWrite
unsigned char	rcv_buff[256]	Receive data buffer	main, IIC_EepRead

### 3.5 Structures

Figure 3.4 shows the structures used in the sample code.

```

struct str_IIC_API_T
{
    unsigned char    SlvAdr;           /* Slave address */
                                   /* Since the low-order bit is the R/W bit, it should always be set to 0. */
    unsigned short   PreCnt;          /* Memory address counter */
    unsigned char    *pPreData;       /* Pointer to memory address storage buffer */
                                   /* On write: Address in EEPROM to which data is written (write destination) */
                                   /* On read: Address in EEPROM from which data is read (read source) */
    unsigned long    RWCnt;          /* Data counter */
                                   /* On write: Number of data items to be written to EEPROM */
                                   /* On read: Number of data items to be read from EEPROM */
    unsigned char    *pRWData;       /* Pointer to data storage buffer */
                                   /* On write: Data storage source for data to be written to EEPROM */
                                   /* On read: Data storage destination for data to be read from EEPROM */
};

typedef struct str_IIC_API_T IIC_API_T;
    
```

**Figure 3.4 Structures Used in Sample Code**

### 3.6 Functions

Table 3.5 lists the functions defined in the sample code.

**Table 3.5 Functions**

Function Name	Overview
mcu_init	CPU initialization
clock_setting	CPU clock settings
peripheral_init	Peripheral function initialization
SCI_init	Serial communications interface (SCI) related initialization
IIC_EepWrite	Writes to the EEPROM
IIC_EepRead	Reads from the EEPROM
Create_StartCondition	Start condition generation
Create_RestartCondition	Restart condition generation
Create_StopCondition	Stop condition generation

### 3.7 Function Specifications

This section lists the specifications of the functions in the sample code.

Name	mcu_init
Overview	CPU initialization
Header	lodefine.h
Declaration	void mcu_init(void)
Description	Sets the CPU clock.
Arguments	None
Return values	None
Notes	

Name	clock_setting
Overview	Sets the CPU clock.
Header	lodefine.h
Declaration	void clock_setting(void)
Description	<ul style="list-style-type: none"> <li>• Stops the subclock oscillator.</li> <li>• Stops the high-speed clock oscillator.</li> <li>• Sets the oscillator stabilization time for the main clock oscillator to 131,072 cycles.</li> <li>• Sets the PLL oscillator stabilization time to 4,194,304 cycles.</li> <li>• Sets the PLL frequency multiplier to 16x.</li> <li>• Sets the main clock oscillator to the operating state.</li> <li>• Sets the PLL circuit to the operating state.</li> <li>• Sets the system clock to divided by 2, the FlashIF clock to divided by 4, the external bus clock to divided by 4, and the peripheral module clock to divided by 4.</li> <li>• Sets the clock source to be the PLL circuit.</li> </ul>
Arguments	None
Return values	None
Notes	

Name	peripheral_init
Overview	Peripheral function initialization
Header	lodefine.h
Declaration	void peripheral_init(void)
Description	Initializes SCI related items.
Arguments	None
Return values	None
Notes	



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Name	SCI_init
Overview	Serial communications interface (SCI) related initialization
Header	lodefine.h
Declaration	void SCI_init(void)
Description	<ul style="list-style-type: none"><li>• Clears SCI0 module stop function.</li><li>• Sets pins P21 (SSCL0) and P20 (SSDA0) to be used as SCI0 pins.</li><li>• Disables SCI0 serial reception operation (RE) and serial transmission operation (TE).</li><li>• Sets the SCI0 SSCL0 and SSDA0 pins to the high-impedance state.</li><li>• Sets the SCI0 clock to be PCLK/4 clock.</li><li>• Sets SCI0 to serial interface mode, MSB first.</li><li>• Sets the SCI0 baud rate to 100 kHz.</li><li>• Sets the noise filter to use a divided-by-1 clock.</li><li>• Sets SCI0 to simple I<sup>2</sup>C mode.</li><li>• Sets the SCI0 smart card mode selection to serial interface mode.</li><li>• Enables the SCI0 SS#0 pin function.</li><li>• Sets the SCI0 interrupt level to level 1.</li><li>• Clears the SCI0 interrupt request flag.</li><li>• Sets the SCI0 interrupt request enable to interrupts disable.</li></ul>
Arguments	None
Return values	None
Notes	

Name	IIC_EepWrite
Overview	Writes to the EEPROM
Header	lodefine.h
Declaration	void IIC_EepWrite(IIC_API_T iic_buf)
Description	Writes to the EEPROM using simple I <sup>2</sup> C master transmission operation.
Arguments	IIC_API_T iic_buf: Structure used as an argument
Return values	None
Notes	

Name	IIC_EepRead
Overview	Reads from the EEPROM
Header	lodefine.h
Declaration	void IIC_EepRead(IIC_API_T iic_buf)
Description	Reads from the EEPROM using simple I <sup>2</sup> C master transmission operation and master reception operation.
Arguments	IIC_API_T iic_buf: Structure used as an argument
Return values	None
Notes	

Name	Create_StartCondition
Overview	Start condition generation
Header	lodefine.h
Declaration	void Create_StartCondition (void)
Description	Generates a start condition.
Arguments	None
Return values	None
Notes	

## **RX630 Group**    **Communication with EEPROM Using the Serial Communications Interface (Simple I<sup>2</sup>C)**

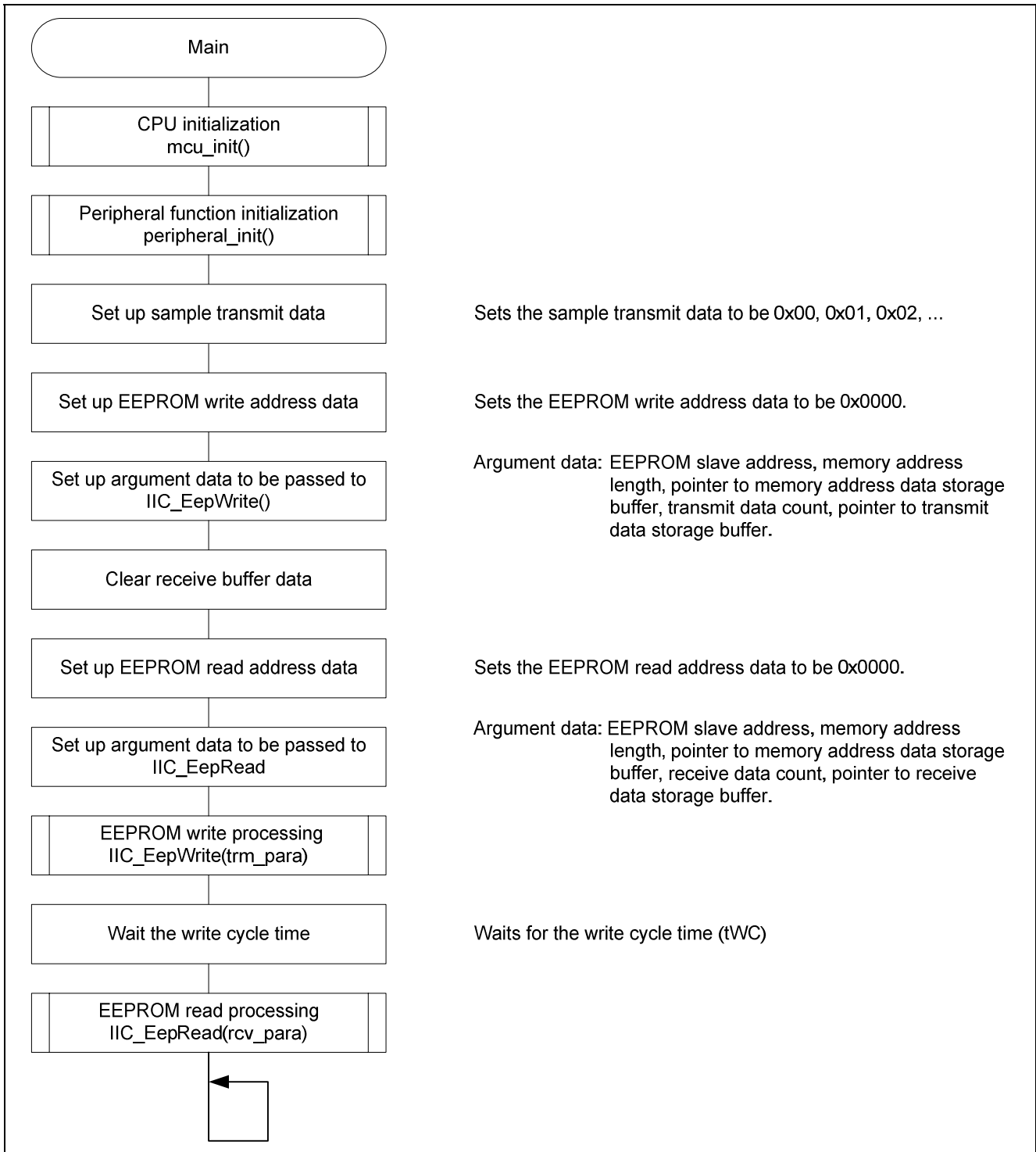
Name	Create_RestartCondition
Overview	Restart condition generation
Header	lodefine.h
Declaration	void Create_RestartCondition (void)
Description	Generates a restart condition.
Arguments	None
Return values	None
Notes	

Name	Create_StopCondition
Overview	Stop condition generation
Header	lodefine.h
Declaration	void Create_StopCondition (void)
Description	Generates a stop condition.
Arguments	None
Return values	None
Notes	

### 3.8 Flowcharts

#### 3.8.1 Main Processing

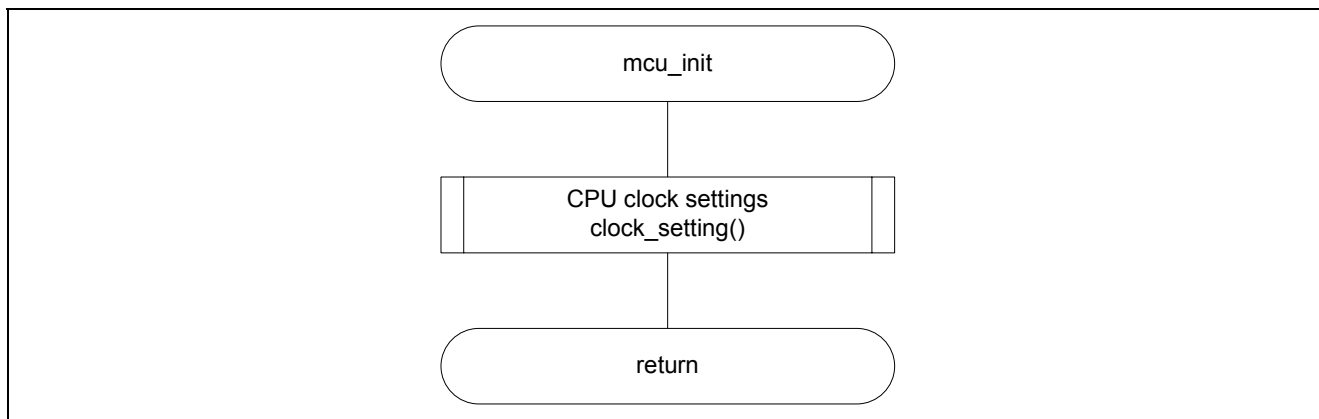
Figure 3.5 shows the main processing flowchart.



**Figure 3.5 Main Processing**

### 3.8.2 CPU Initialization

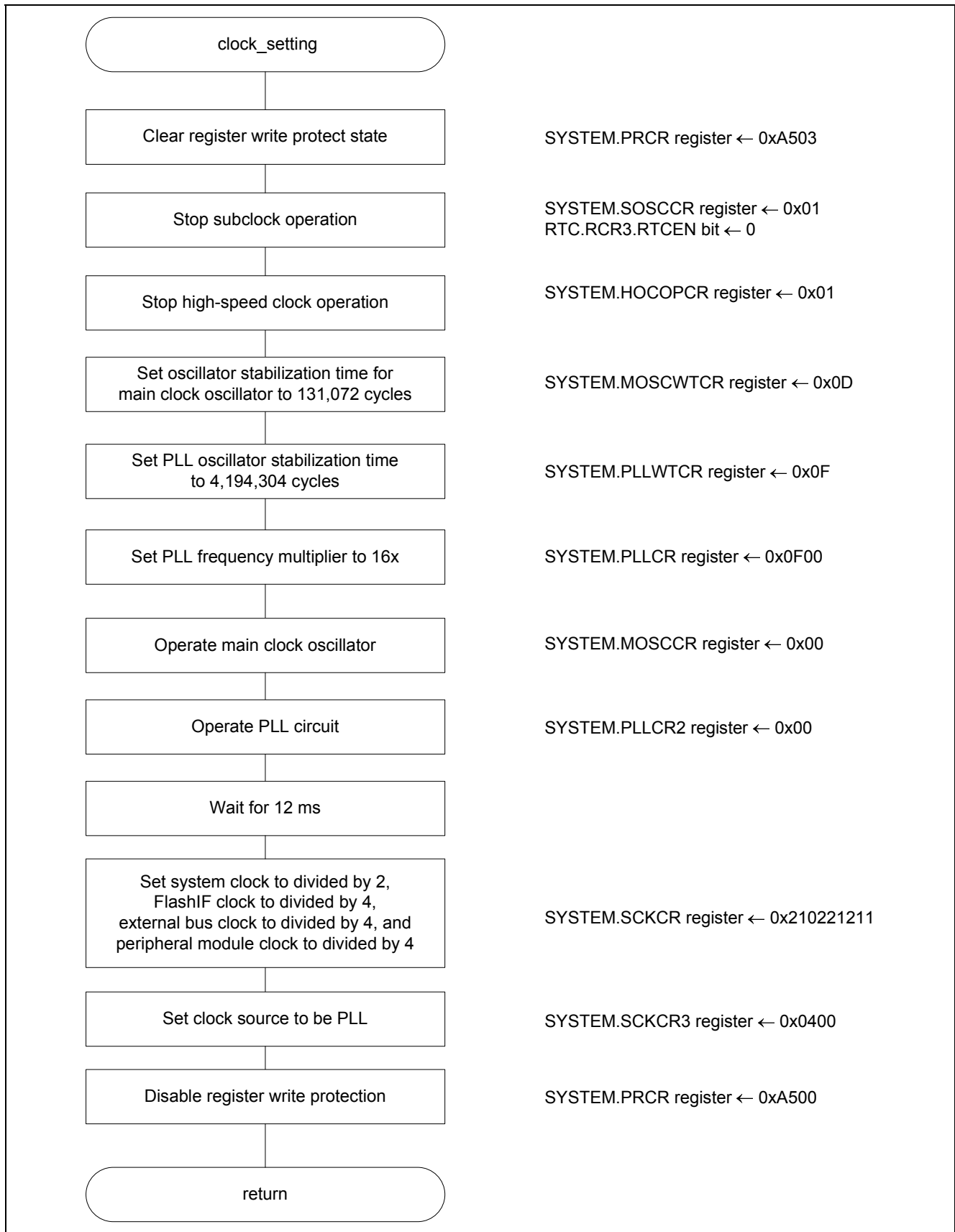
Figure 3.6 shows the flowchart for CPU initialization.



**Figure 3.6 CPU Initialization**

**3.8.3 CPU Clock Settings**

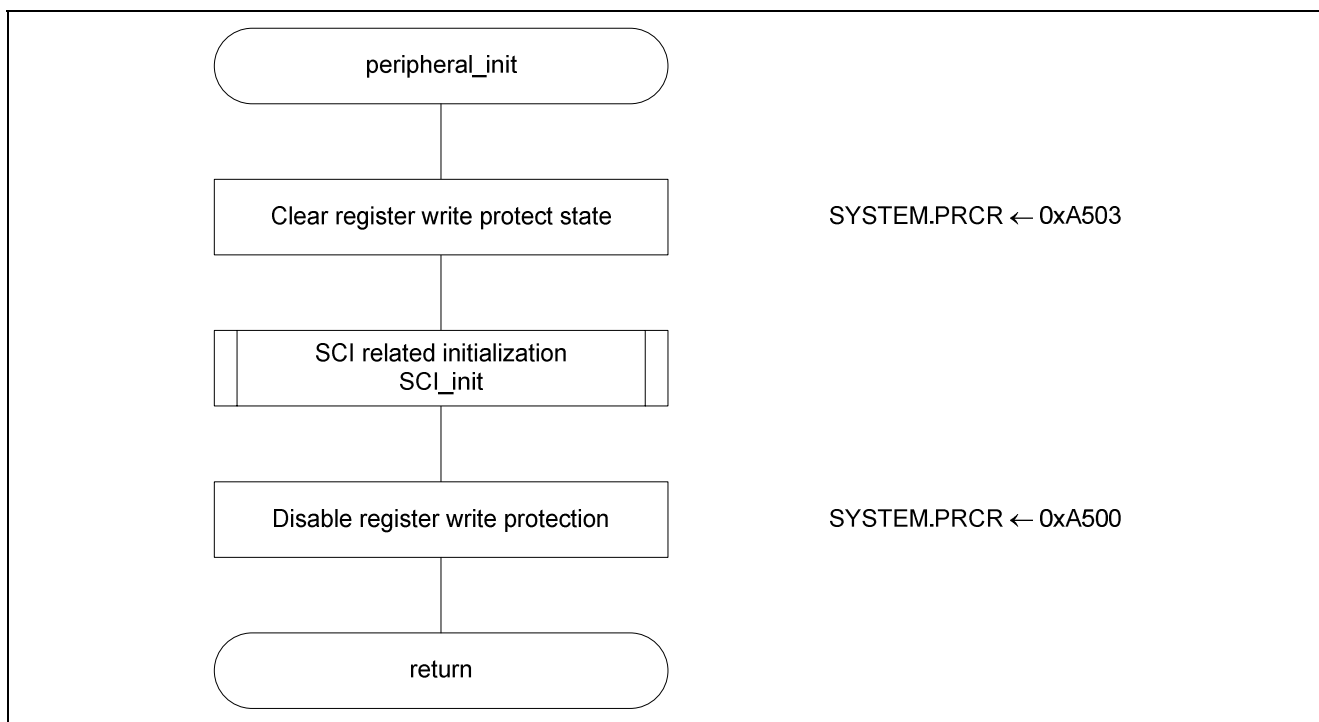
Figure 3.7 shows the flowchart for the CPU clock settings.



**Figure 3.7 CPU Clock Settings**

### 3.8.4 Peripheral Function Initialization

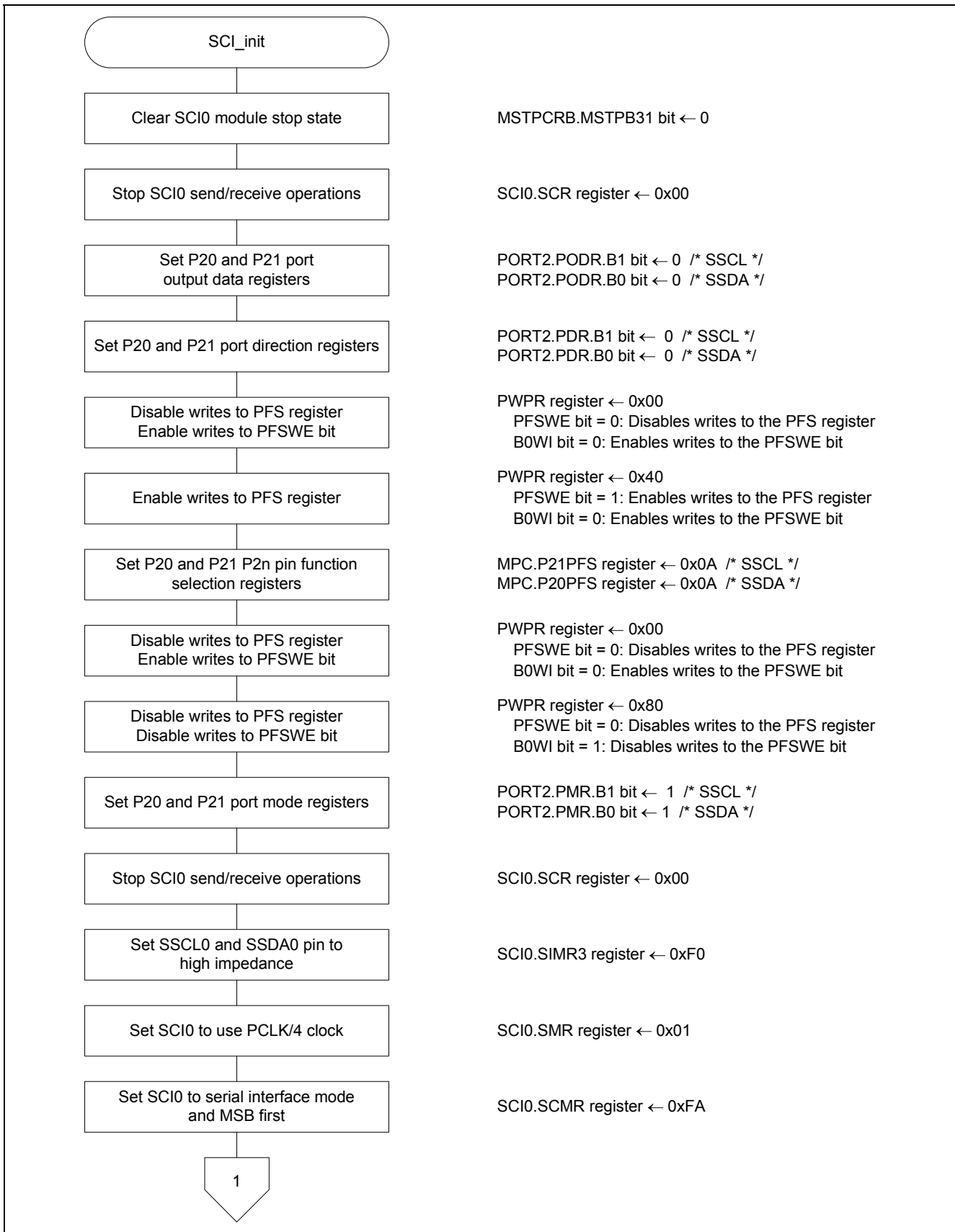
Figure 3.8 shows the flowchart for peripheral function initialization.



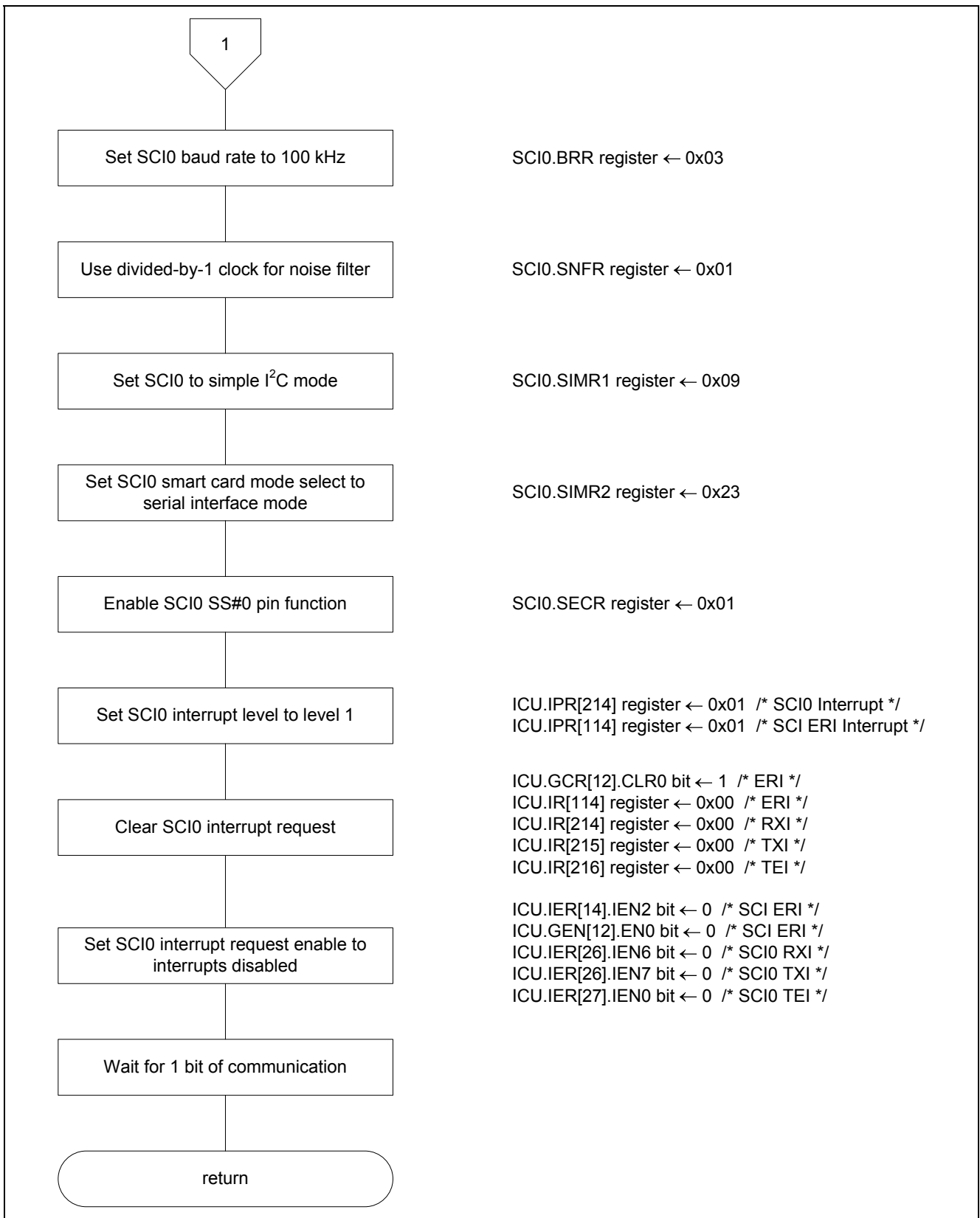
**Figure 3.8 Peripheral Function Initialization**

**3.8.5 Serial Communications Interface (SCI) Related Initialization**

Figures 3.9 and 3.10 show the flowcharts for the serial communications interface (SCI) related initialization.



**Figure 3.9 Serial Communications Interface (SCI) Related Initialization (1)**

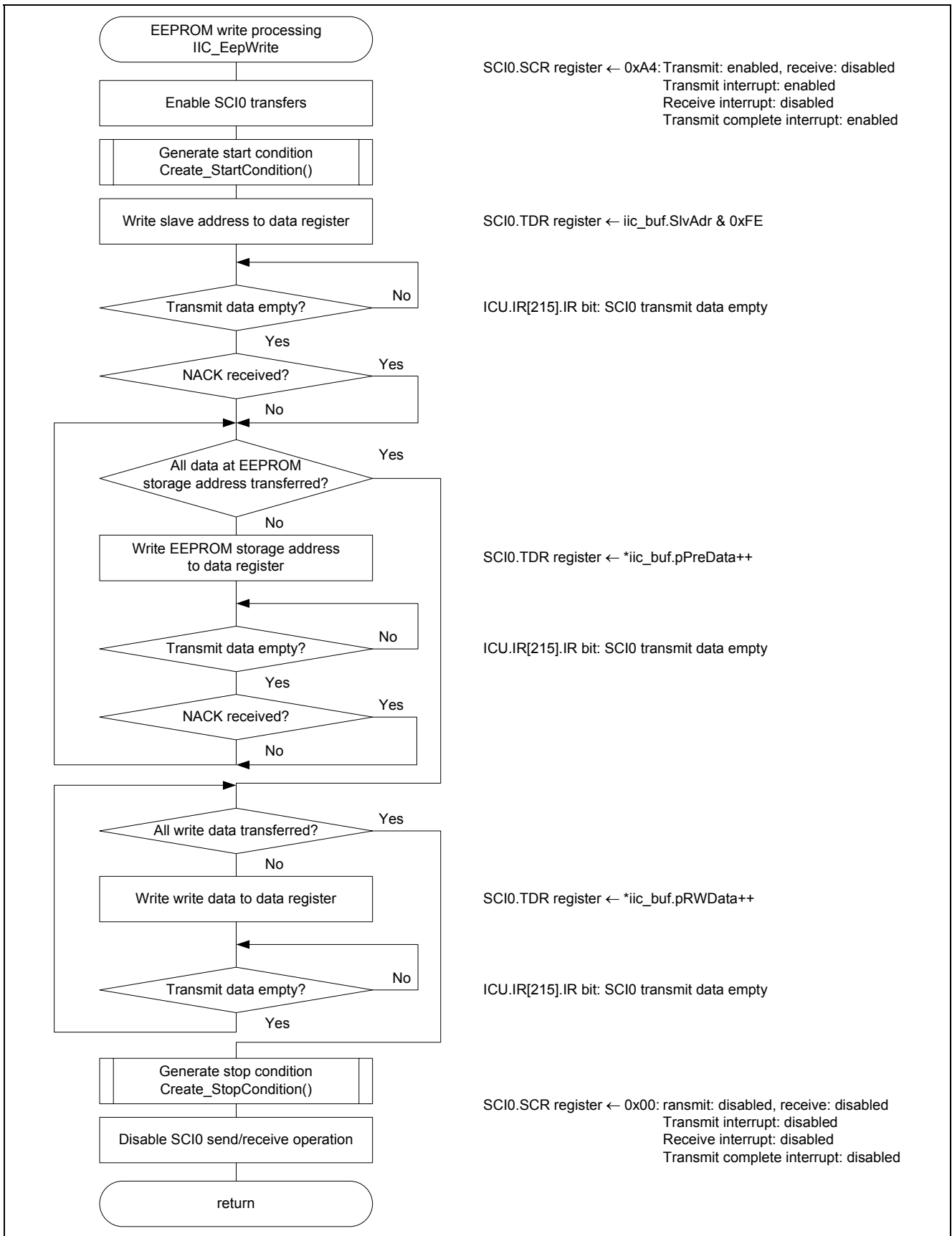


**Figure 3.10 Serial Communications Interface (SCI) Related Initialization (2)**



**3.8.6 EEPROM Write Processing**

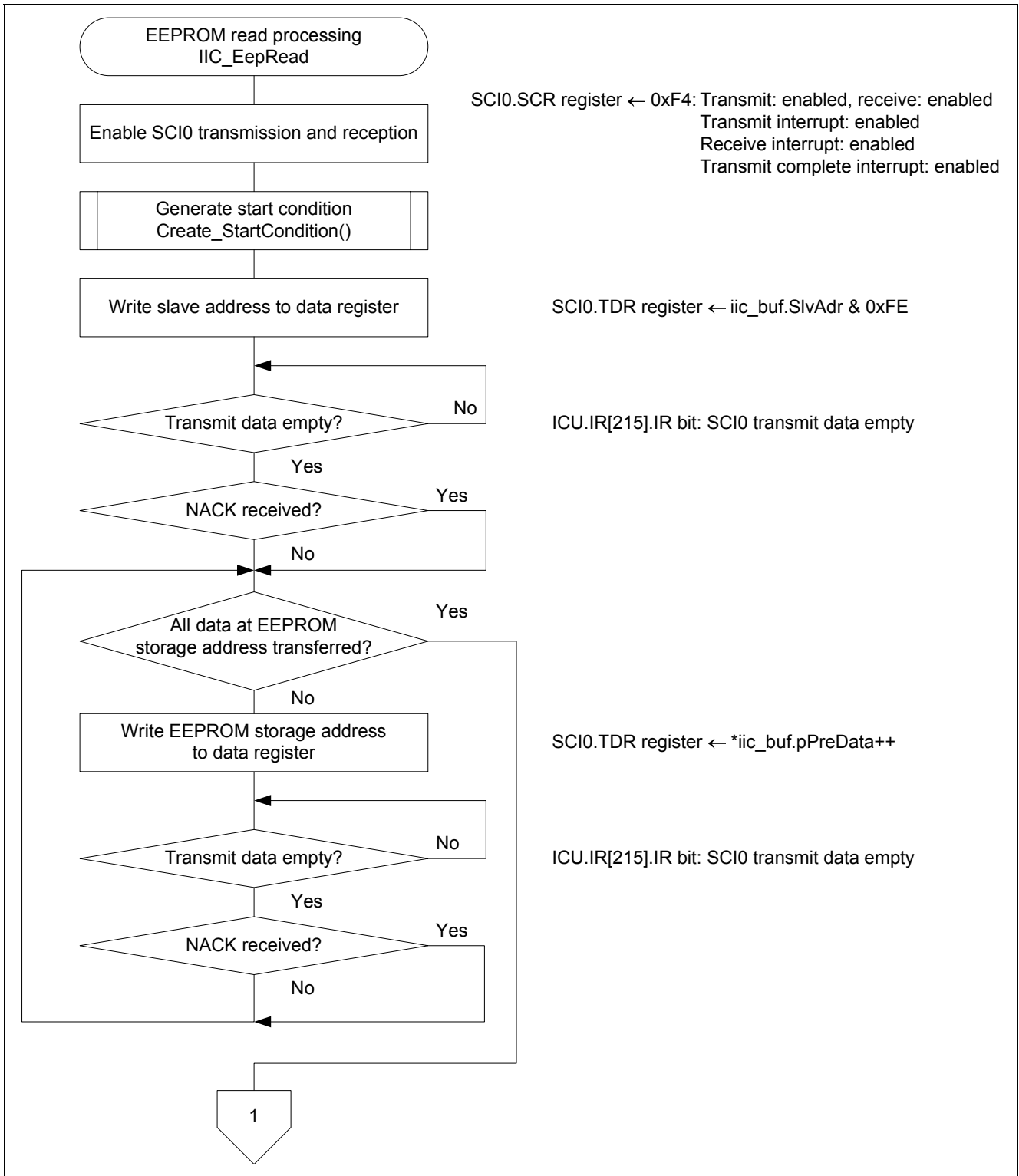
Figure 3.11 shows the flowchart for EEPROM write processing.



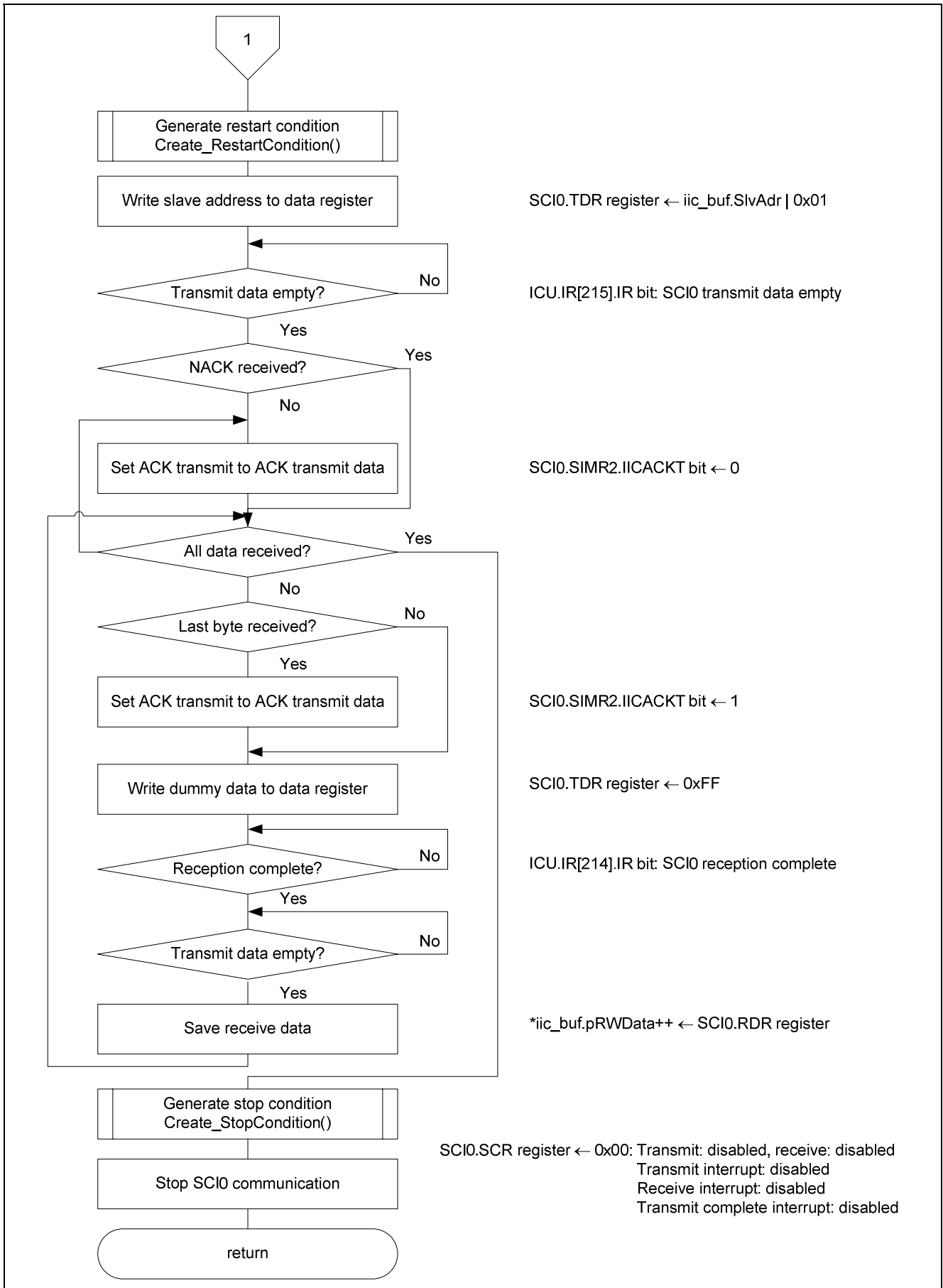
**Figure 3.11 EEPROM Write Processing**

**3.8.7 EEPROM Read Processing**

Figures 3.12 and 3.13 show the flowcharts for EEPROM read processing.



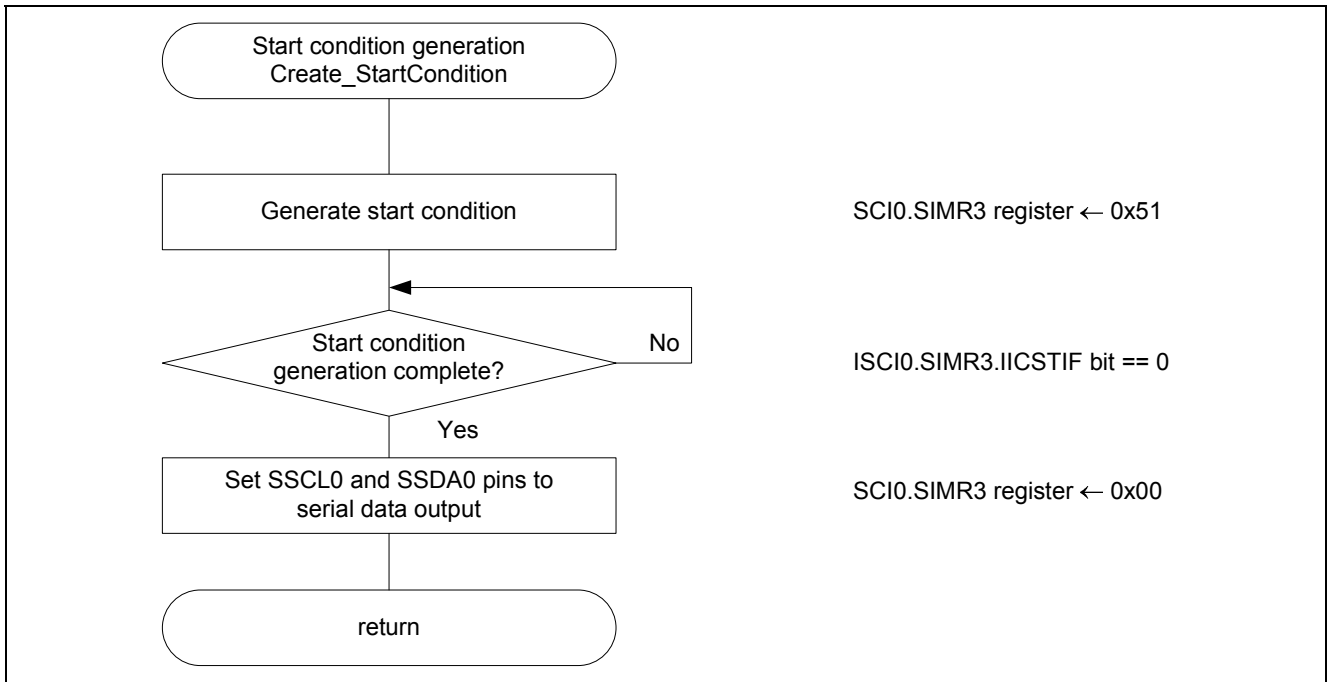
**Figure 3.12 EEPROM Read Processing (1)**



**Figure 3.13 EEPROM Read Processing (2)**

**3.8.8 Start Condition Generation**

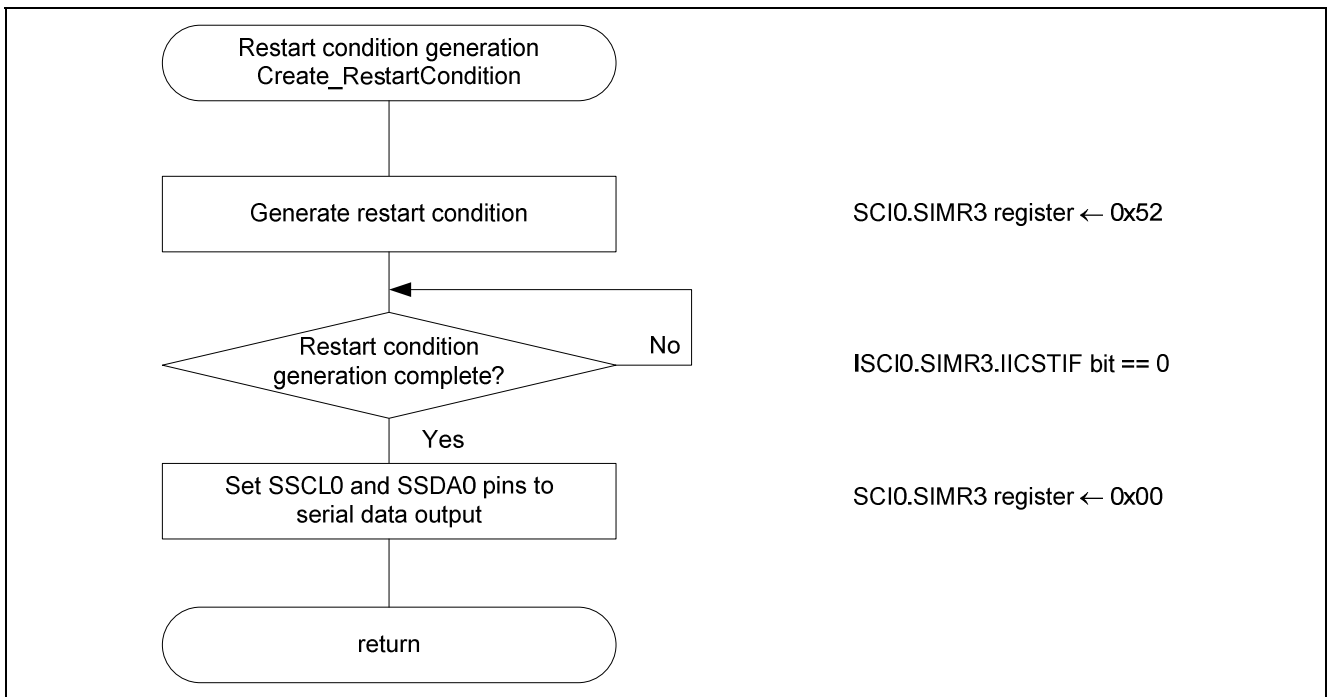
Figure 3.14 shows the flowchart for start condition generation.



**Figure 3.14 Start Condition Generation**

**3.8.9 Restart Condition Generation**

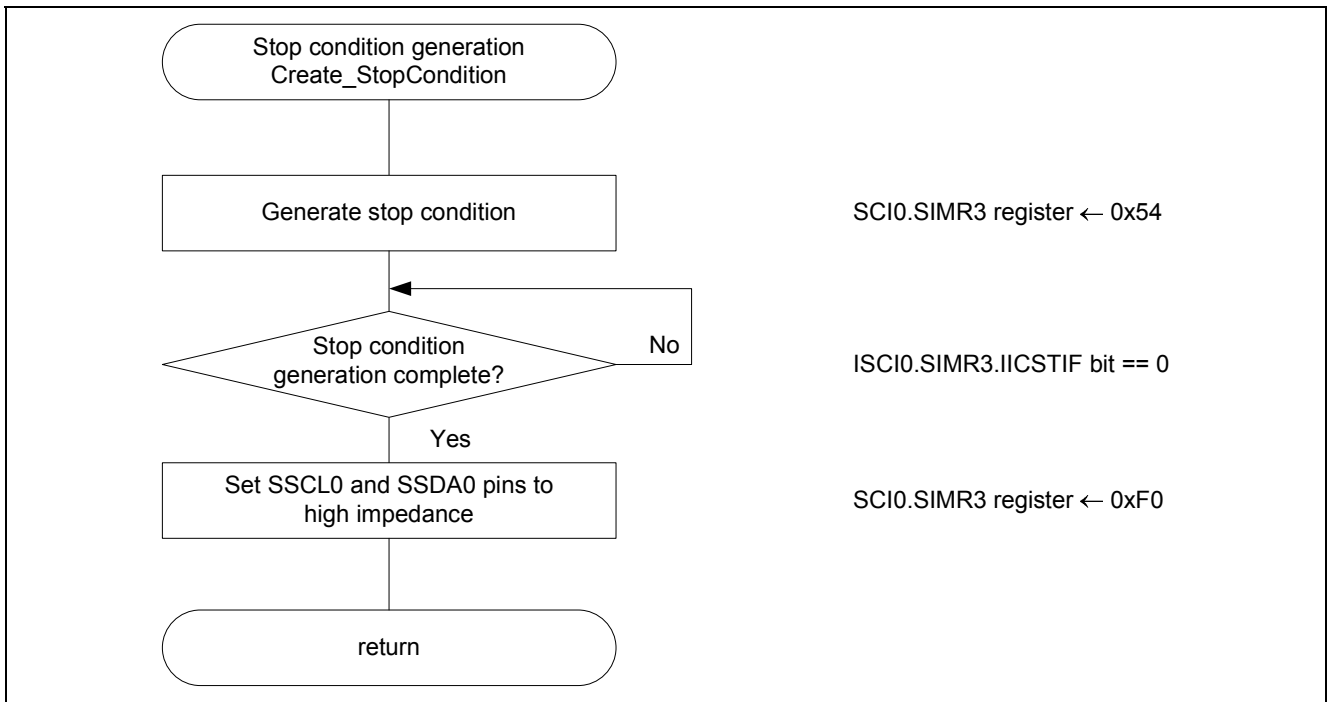
Figure 3.15 shows the flowchart for restart condition generation.



**Figure 3.15 Restart Condition Generation**

**3.8.10 Stop Condition Generation**

Figure 3.16 shows the flowchart for stop condition generation.



**Figure 3.16 Stop Condition Generation**

#### **4. Sample Programs**

The sample program can be downloaded from the Renesas Electronics Web site.

#### **5. Reference Documents**

- RX630 Group User's Manual: Hardware, Rev.1.00  
(The latest version can be downloaded from the Renesas Electronics Web site.)
- Technical Updates/Technical News  
(The latest information can be downloaded from the Renesas Electronics Web site.)
- C Compiler Manual  
RX Family C/C++ Compiler Package User's Manual V.1.0.1.0  
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- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

### 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

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Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

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